

FEATURES

- **Low Supply Voltage Range: 1.8 V to 3.6 V**
- **Ultralow-Power Consumption:**
 - Active Mode: 160 μ A at 1 MHz, 2.2 V
 - Standby Mode: 0.9 μ A
 - Off Mode (RAM Retention) : 0.1 μ A
- **Contains Frequency-Hopping Firmware for Dolphin Reference Design**
- **Firmware Resides in ROM-Based Program Memory and is Fixed**
- **Simple UART Interface to an External Host/System Microcontroller**
- **Pre-Defined Protocol for Communication with**

- an External Host/System Microcontroller**
- **Five Power-Saving Modes**
- **Wake-Up From Standby Mode in less than 6 μ s**
- **16-Bit RISC Architecture, 125-ns Instruction Cycle Time**
- **Serial Communication Interface (USART), Software Selects Asynchronous UART or Synchronous SPI**
- **Available in 64-Pin Quad Flat Pack (QFP)**
- **For Complete Dolphin Product Description, See the *Dolphin Frequency Hopping Spread Spectrum Evaluation Kit Hardware and Software User's Guide (SLLU090)***

DESCRIPTION

The DBB03A is a baseband ASIC for the "Dolphin" reference design. The firmware for the Dolphin reference design resides in the ROM-based program memory of the DBB03A, and thus can be readily interfaced with a TRF6903 single-chip RF Transceiver to generate a frequency hopping wireless UART "Dolphin" reference design chipset. This is illustrated in [Figure 1](#).

The DBB03A baseband ASIC in addition to being a RF baseband processor is also responsible for communications with an external host/system microcontroller. In a typical end user application, the Dolphin chipset will be connected up to an external host/system microcontroller that will send configuration messages, RF transmission messages into the Dolphin chipset, or receive status, RF messages received from the Dolphin chipset.

Any catalog low-cost host/system microcontroller can be interfaced to the Dolphin chipset as long as the Dolphin host interface protocol for communication is adhered to. (See Application Note Dolphin - Frequency Hopping Spread Spectrum Chipset Host Interface Protocol TI Literature SWRA043) Texas Instruments recommends its ultra-low power MSP430 series of microcontrollers to interface with Dolphin.

The interface between the DBB03A baseband ASIC and an external host/system microcontroller is a simple UART consisting of RX and TX data lines. (See Application Note *Interfacing Dolphin to an External System Microcontroller*, TI Literature SWRA045).



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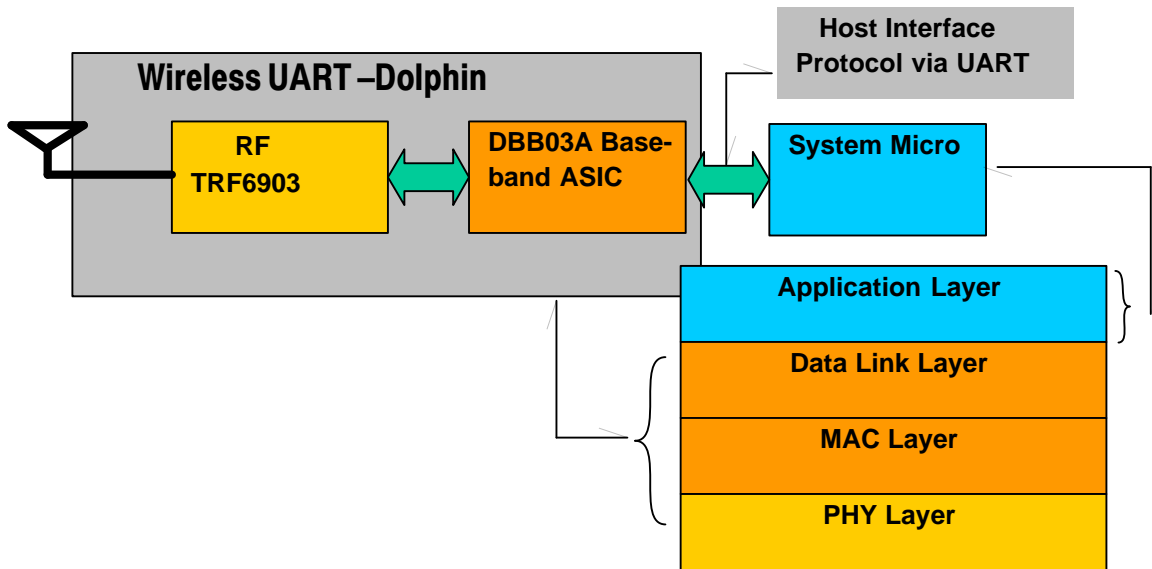


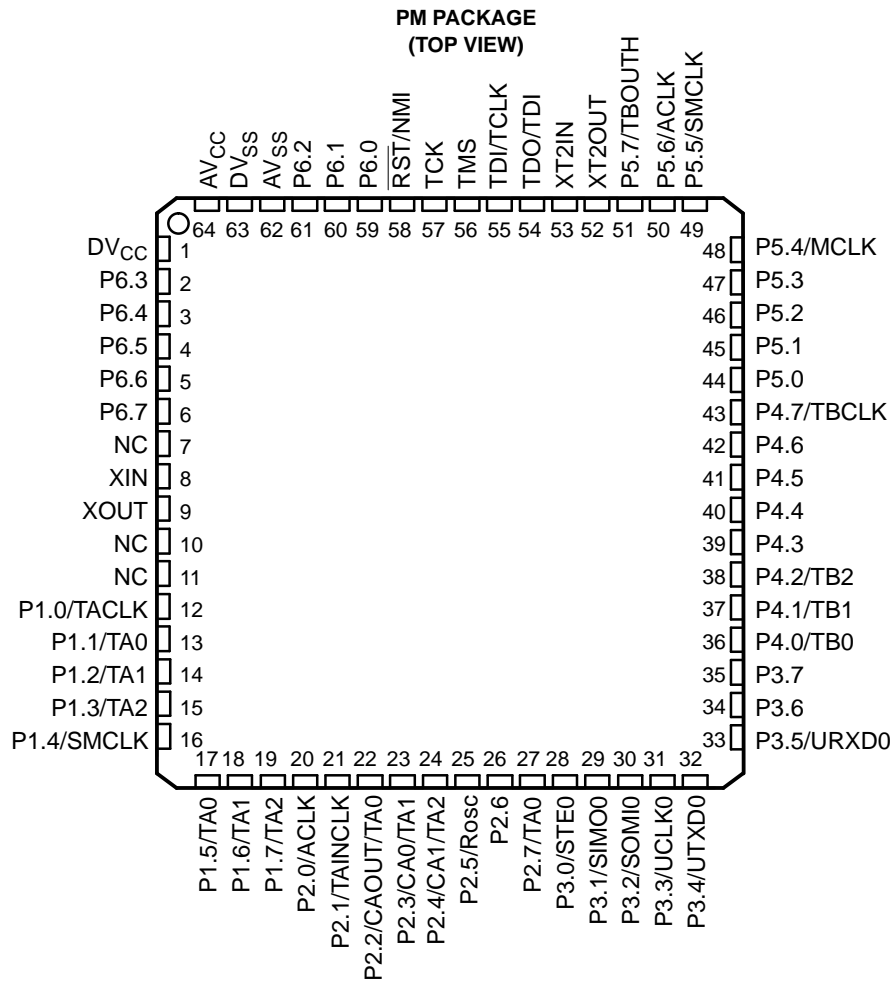
Figure 1. DBB03A - Baseband ASIC for the Dolphin Chipset

The Wireless UART Dolphin chipset is a true Data-In/RF-out and RF-in/Data-out solution with all aspects of data management and frequency hopping implemented in firmware residing on the DBB03A. As illustrated in [Figure 1](#), the DBB03A baseband ASIC contains the complete firmware for Dolphin (PHYSical, MAC and the Data Link layer), while the application layer protocol is handled by the external Host/System Microcontroller.

AVAILABLE OPTIONS

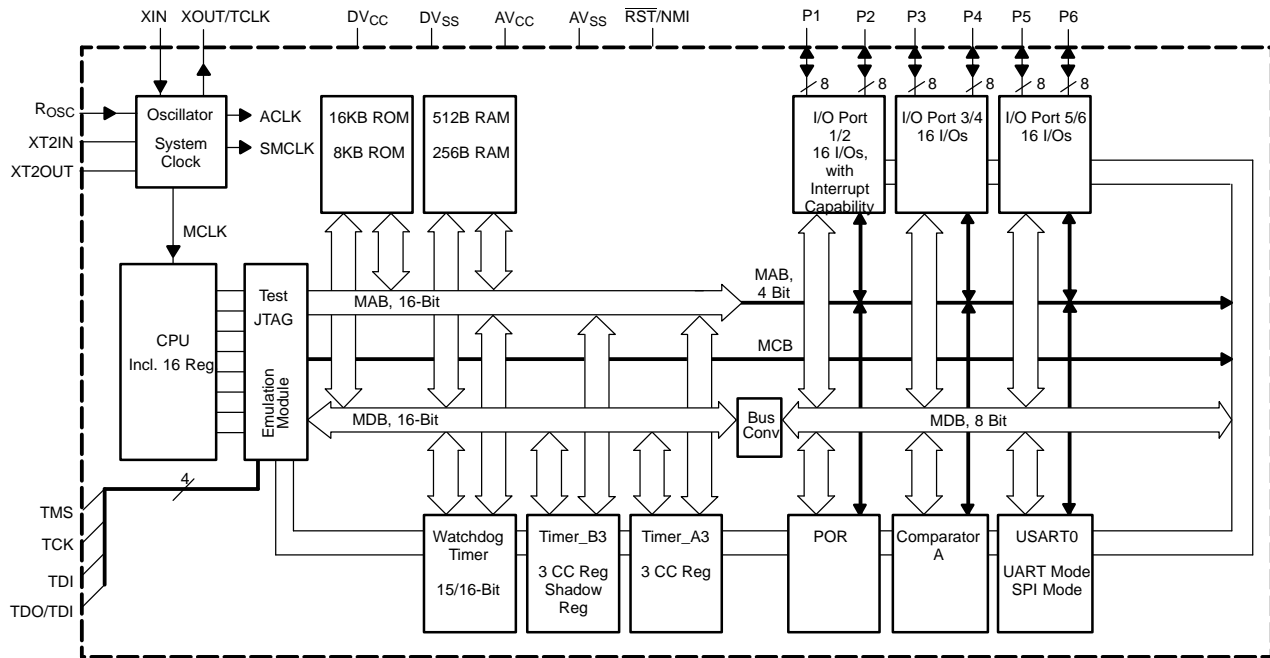
T_A	PACKAGE	ORDER NUMBER
-40°C to 85°C	Plastic 64-pin QFP (PM)	DBB03A IPM

PIN DESIGNATION, DBB03A Baseband ASIC



NC – No internal connection

FUNCTIONAL BLOCK DIAGRAMS: DBB03A



DEVICE INFORMATION

TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
AV _{CC}	64		Supply voltage, positive terminal. AV _{CC} and DV _{CC} are internally connected together.
AV _{SS}	64		Supply voltage, negative terminal. AV _{SS} and DV _{SS} are internally connected together.
DV _{CC}	1		Supply voltage, positive terminal. AV _{CC} and DV _{CC} are internally connected together.
DV _{SS}	63		Supply voltage, negative terminal. AV _{SS} and DV _{SS} are internally connected together.
P1.0/TACLK	12	I/O	General-purpose digital I/O pin/Timer_A, clock signal TACLK input
P1.1/TA0	13	I/O	General-purpose digital I/O pin/Timer_A, capture: CCI0A input, compare: Out0 output
P1.2/TA1	14	I/O	General-purpose digital I/O pin/Timer_A, capture: CCI1A input, compare: Out1 output
P1.3/TA2	15	I/O	General-purpose digital I/O pin/Timer_A, capture: CCI2A input, compare: Out2 output
P1.4/SMCLK	16	I/O	General-purpose digital I/O pin/SMCLK signal output
P1.5/TA0	17	I/O	General-purpose digital I/O pin/Timer_A, compare: Out0 output
P1.6/TA1	18	I/O	General-purpose digital I/O pin/Timer_A, compare: Out1 output
P1.7/TA2	19	I/O	General-purpose digital I/O pin/Timer_A, compare: Out2 output
P2.0/ACLK	20	I/O	General-purpose digital I/O pin/ACLK output
P2.1/TAINCLK	21	I/O	General-purpose digital I/O pin/Timer_A, clock signal at INCLK
P2.2/CAOUT/TA0	22	I/O	General-purpose digital I/O pin/Timer_A, capture: CCI0B input/Comparator_A output
P2.3/CA0/TA1	23	I/O	General-purpose digital I/O pin/Timer_A, compare: Out1 output/Comparator_A input
P2.4/CA1/TA2	24	I/O	General-purpose digital I/O pin/Timer_A, compare: Out2 output/Comparator_A input
P2.5/R _{OSC}	25	I/O	General-purpose digital I/O pin/input for external resistor defining the DCO nominal frequency
P2.6	26	I/O	General-purpose digital I/O pin

DEVICE INFORMATION (continued)
TERMINAL FUNCTIONS (continued)

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
P2.7/TA0	27	I/O	General-purpose digital I/O pin/Timer_A, compare: Out0 output
P3.0/STE0	28	I/O	General-purpose digital I/O pin/slave transmit enable - USART0/SPI mode
P3.1/SIMO0	29	I/O	General-purpose digital I/O pin/slave in/master out of USART0/SPI mode
P3.2/SOMI0	30	I/O	General-purpose digital I/O pin/slave out/master in of USART0/SPI mode
P3.3/UCLK0	31	I/O	General-purpose digital I/O pin/external clock input - USART0/UART or SPI mode, clock output - USART0/SPI mode
P3.4/UTXD0	32	I/O	General-purpose digital I/O pin/transmit data out - USART0/UART mode
P3.5/URXD0	33	I/O	General-purpose digital I/O pin/receive data in - USART0/UART mode
P3.6	34	I/O	General-purpose digital I/O pin
P3.7	35	I/O	General-purpose digital I/O pin
P4.0/TB0	36	I/O	General-purpose digital I/O pin/Timer_B, capture: CCI0A/B input, compare: Out0 output
P4.1/TB1	37	I/O	General-purpose digital I/O pin/Timer_B, capture: CCI1A/B input, compare: Out1 output
P4.2/TB2	38	I/O	General-purpose digital I/O pin/Timer_B, capture: CCI2A/B input, compare: Out2 output
P4.3	39	I/O	General-purpose digital I/O pin
P4.4	40	I/O	General-purpose digital I/O pin
P4.5	41	I/O	General-purpose digital I/O pin
P4.6	42	I/O	General-purpose digital I/O pin
P4.7/TBCLK	43	I/O	General-purpose digital I/O pin/Timer_B, clock signal TBCLK input
P5.0	44	I/O	General-purpose digital I/O pin
P5.1	45	I/O	General-purpose digital I/O pin
P5.2	46	I/O	General-purpose digital I/O pin
P5.3	47	I/O	General-purpose digital I/O pin
P5.4/MCLK	48	I/O	General-purpose digital I/O pin/main system clock MCLK output
P5.5/SMCLK	49	I/O	General-purpose digital I/O pin/submain system clock SMCLK output
P5.6/ACLK	50	I/O	General-purpose digital I/O pin/auxiliary clock ACLK output
P5.7/TBOUT H	51	I/O	General-purpose digital I/O pin/switch all PWM digital output ports to high impedance - Timer_B7 TB0 to TB2
P6.0	59	I/O	General-purpose digital I/O pin
P6.1	60	I/O	General-purpose digital I/O pin
P6.2	61	I/O	General-purpose digital I/O pin
P6.3	2	I/O	General-purpose digital I/O pin
P6.4	3	I/O	General-purpose digital I/O pin
P6.5	4	I/O	General-purpose digital I/O pin
P6.6	5	I/O	General-purpose digital I/O pin
P6.7	6	I/O	General-purpose digital I/O pin
RST/NMI	58	I	Reset input, nonmaskable interrupt input port
TCK	57	I	Test clock. TCK is the clock input port for device programming test.
TDI/TCLK	55	I	Test data input or test clock input. TDI is used as a data input port. The device protection fuse is connected to TDI.
TDO/TDI	54	I/O	Test data output port. TDO/TDI data output
TMS	56	I	Test mode select. TMS is used as an input port for device test.
NC	7, 10, 11		No internal connection
XIN	8	I	Input port for crystal oscillator XT1. Standard or watch crystals can be connected.
XOUT	9	O	Output terminal of crystal oscillator XT1
XT2IN	53	I	Input port for crystal oscillator XT2. Only standard crystals can be connected.
XT2OUT	52	O	Output terminal of crystal oscillator XT2

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
DBB03AIPM	NRND	LQFP	PM	64		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
DBB03AIPMR	NRND	LQFP	PM	64		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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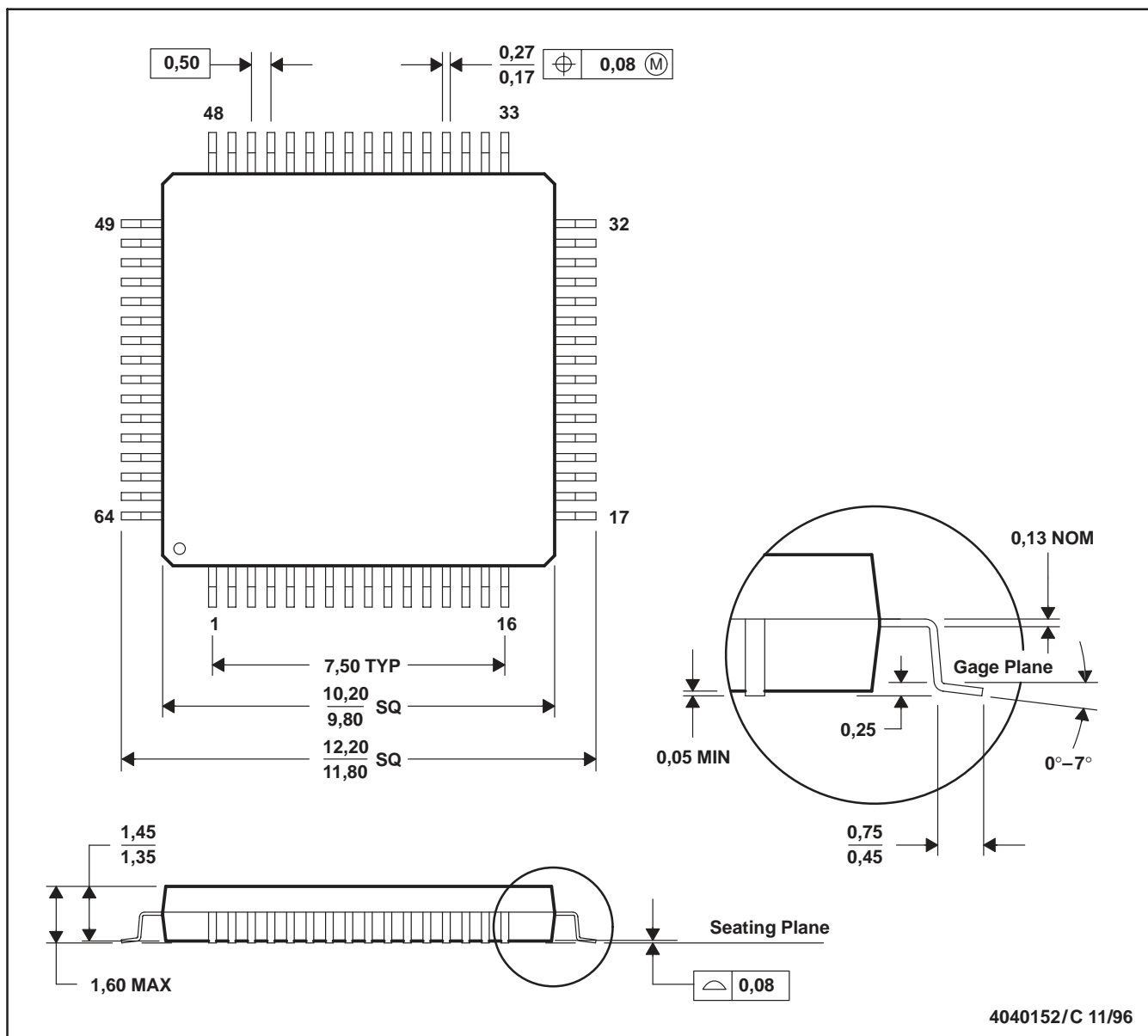
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PM (S-PQFP-G64)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026
 D. May also be thermally enhanced plastic with leads connected to the die pads.

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